

メタルマスク : 0.1mm
 開口部 : TERM.(0.7X0.3)
 NAIL(1.0X0.3)
 METAL MASK THICKNESS : 0.1mm
 OPENING AREA : TERM.(0.7X0.3)
 NAIL(1.0X0.3)

16.5	17.08	15.5	17.7	503480-3200	32
13.5	14.08	12.5	14.7	503480-2600	26
12.5	13.08	11.5	13.7	503480-2400	24
11.5	12.08	10.5	12.7	503480-2200	22
10.5	11.08	9.5	11.7	503480-2000	20
9.5	10.08	8.5	10.7	503480-1800	18
9.0	9.58	8.0	10.2	503480-1700	17
8.5	9.08	7.5	9.7	503480-1600	16
7.5	8.08	6.5	8.7	503480-1400	14
6.5	7.08	5.5	7.7	503480-1200	12
5.5	6.08	4.5	6.7	503480-1000	10
4.5	5.08	3.5	5.7	503480-0800	8
3.5	4.08	2.5	4.7	503480-0600	6
3.0	3.58	2.0	4.2	503480-0500	5
2.5	3.08	1.5	3.7	503480-0400	4
D	C	B	A	EMBOSSED PACKAGE	極数
				オーダー番号 ORDER NO.	CIRCUIT

CONNECTOR SERIES No. 503480-***09

REVISED EC NO: KOR2015-0144 DRWN:YRK/IM 2015/06/05 CHKD:KSK/IM 2015/06/05 APPR:YSK/IM02 2015/06/08	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
				DRAWN BY THIRAYAMA	DATE 2009/12/11	TITLE 0.5 FPC CONN. E/O BACKFLIP H=1.0MM ASSEMBLY					
				CHECKED BY NMATSUURA	DATE 2009/12/11	molex					
				APPROVED BY KMORIKAWA	DATE 2010/10/13						
		ANGULAR ± 1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-503480-001		1 OF 2			
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

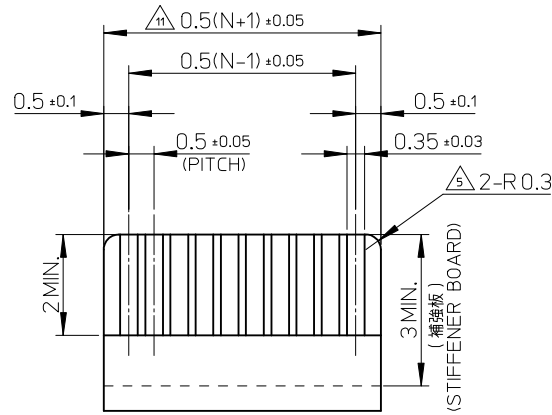
NOTES

1. 部品構成
 PART COMPOSITION
 ハウジング・・・材質：液晶ポリマー（LCP）、ガラス充填、UL94V-0、ナチュラル（白）
 HOUSING MATERIAL: LIQUID CRYSTAL POLYMER(LCP) GLASS FILLED, UL94V-0, NATURAL(WHITE)
 ターミナル・・・材質：燐青銅
 TERMINAL MATERIAL: PHOSPHOR BRONZE
 コンタクト部：部分金メッキ（0.1μm以上）
 テール部：部分金メッキ
 下地：ニッケルメッキ（1.0μm以上）
 CONTACT AREA: SEPARATED GOLD PLATING (0.1 MICROMETER MINIMUM)
 SOLDER TAIL AREA: SEPARATED GOLD PLATING
 UNDERPLATE: NICKEL OVERALL (1.0 MICROMETER MINIMUM)
 アクチュエータ・・・材質：ポリアミド（PA）、ガラス充填、UL94 HB、黒色
 ACTUATOR MATERIAL: POLYAMIDE(PA) GLASS FILLED, UL94 HB, BLACK
 ネイル・・・材質：燐青銅
 NAIL MATERIAL: PHOSPHOR BRONZE
 テール部：錫メッキ（1.0μm以上）
 下地：ニッケルメッキ（1.0μm以上）
 SOLDER TAIL AREA: TIN OVERALL (1.0 MICROMETER MINIMUM)
 UNDERPLATE: NICKEL OVERALL (1.0 MICROMETER MINIMUM)

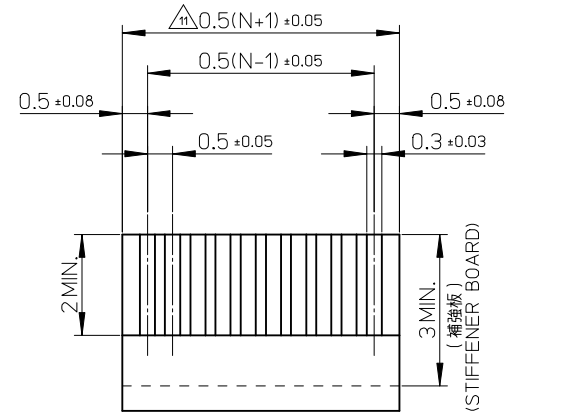
2. 基板実装前にアクチュエータを操作しないで下さい。
 PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
 3. 必ずFPCを挿入してからアクチュエータを操作して下さい。
 PLEASE OPERATE THE ACTUATOR AFTER INSERTING THE FPC INTO THE CONNECTOR.
 4. FPCについて
 ABOUT FPC
 補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
 接着剤は熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
 RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
 NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

- 打抜き方向は導体側から補強板側を推奨致します。
 導体部については軟銅箔35μmを推奨致します。
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
 RECOMMENDED CONDUCTOR SPECIFICATION:
 THICKNESS OF SOFT COPPER FOIL: 35MICROMETER
 △ RO.3は、FPC導体部にかからないこと。
 RO.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

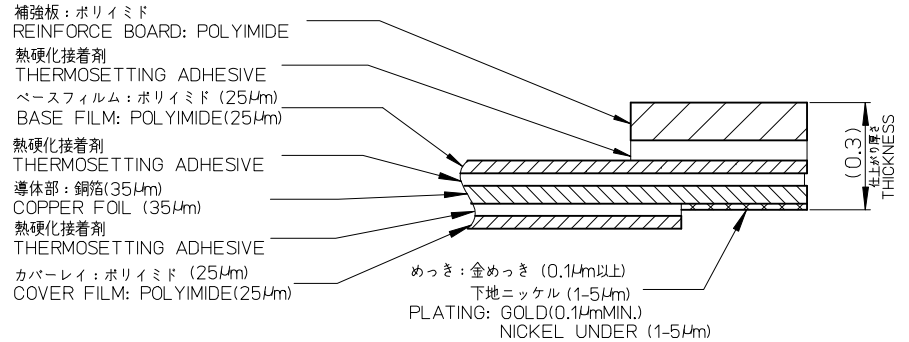
6. ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT
 7. 平坦度：0.1以下
 COPLANARITY : 0.1 MAXIMUM
 8. 製造上の都合により機能に阻害しない部位の形状を変更する可能性があります。
 PLEASE RECOGNIZE A POSSIBILITY TO CHANGE THE SHAPE OF THE PART THAT DOES NOT OBSTRUCT A FUNCTION, BY CIRCUMSTANCES IN OUR PRODUCTION.
 9. 本製品の納入状態はアクチュエータが開いた状態となります。
 THIS PRODUCT IS DELIVERED WITH THE ACTUATOR IN THE OPEN POSITION.
 10. 本製品は両面(上面、下面)接触に対応しております。
 THIS PRODUCT IS DUAL-CONTACT (TOP AND BOTTOM-CONTACTS) TYPE CONNECTOR.
 △ FPC幅が0.5(N+1)+0.02を超える場合、FPC挿入性の事前確認をお願いします。
 PLEASE CONFIRM TO INSERT FPC IN ADVANCE WHEN FPC WIDTH IS OVER 0.5(N+1)+0.02.



適合FPC推奨寸法
 APPLICABLE FPC
 RECOMMENDED DIMENSION
 N: 極数
 N: CIRCUITS
 (仕上がり厚さ: 0.3±0.05) : 30極以下に適用
 (THICKNESS: 0.3±0.05) : 30 OR LESS CIRCUITS
 (仕上がり厚さ: 0.3±0.03) : 31極以上に適用
 (THICKNESS: 0.3±0.03) : 31 OR OVER CIRCUITS



適合FFC推奨寸法
 APPLICABLE FFC
 RECOMMENDED DIMENSION
 N: 極数
 N: CIRCUITS
 (仕上がり厚さ: 0.3±0.05) : 30極以下に適用
 (THICKNESS: 0.3±0.05) : 30 OR LESS CIRCUITS
 (仕上がり厚さ: 0.3±0.03) : 31極以上に適用
 (THICKNESS: 0.3±0.03) : 31 OR OVER CIRCUITS



FPC構成推奨仕様
 STRUCTURE OF FPC

SEE SHEET1 EC NO: KOR2015-0144 DRWN:YRK/IM 2015/06/05 CHKD:SK/IM 2015/06/05 APPR:YSK/IM02 2015/06/08	QUALITY SYMBOLS ▽=0 ◇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY THIRAYAMA	DATE 2009/12/11	TITLE 0.5 FPC CONN. E/O BACKFLIP H=1.0MM ASSEMBLY			
		4 PLACES ± ---	± ---	CHECKED BY NMATSUURA	DATE 2009/12/11	molex			
		3 PLACES ± 0.2	± ---	APPROVED BY KMORIKAWA	DATE 2010/10/13				
2 PLACES ± 0.25	± ---	ANGULAR ± 1 °		MATERIAL NO.	DOCUMENT NO.	SHEET NO.			
1 PLACE ± 0.3	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET1	SD-503480-001	2 OF 2			
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				